

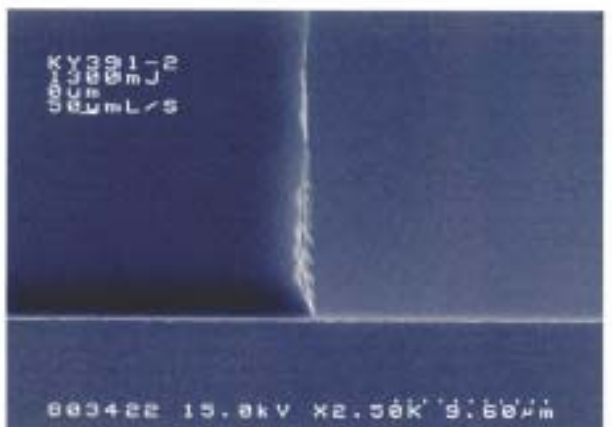
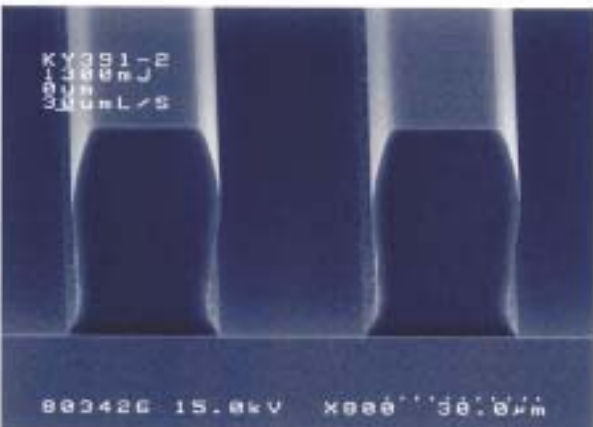
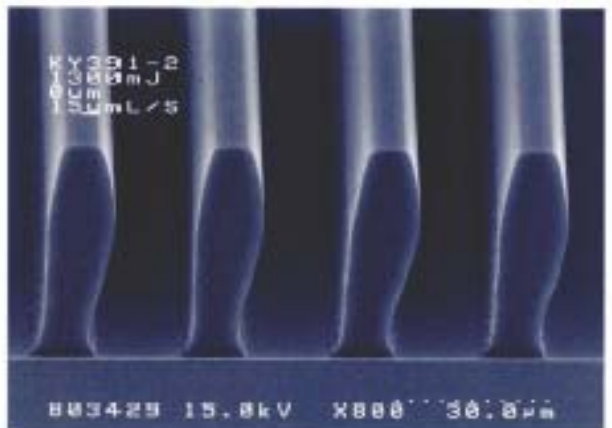
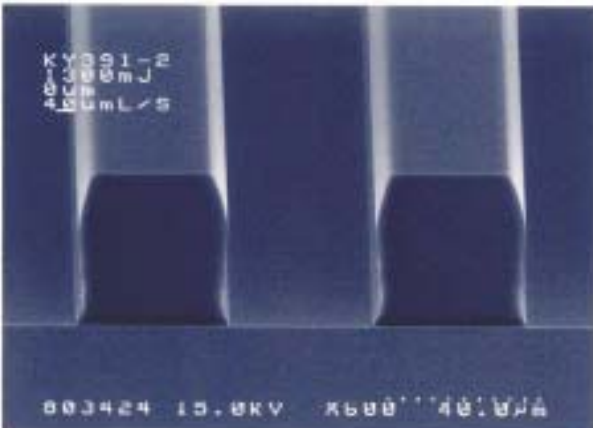
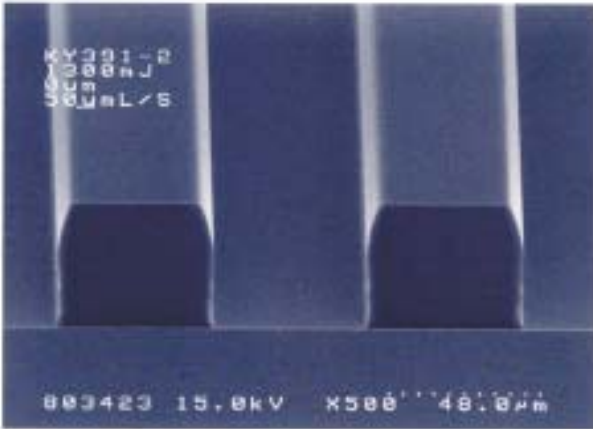
SIPR-7121

Cu

Sputtering Substrate



Thickness : 60μm Prebake : 130°C x 300sec Dev : SSFD-238 50sec x12 puddles
Exposure : NIKON NSR1755i7A (NA=0.50, σ=0.60); 1500mJ PEB : 80°C x 120 sec.



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Cu

Sputtering Substrate



Thickness : 60 μ m Prebake : 130 $^{\circ}$ C x 300sec Dev:SSFD-238(TMAH 2.38%) 50sec x12puddles
Exposure : NIKON NSR1755i7A (NA=0.50, σ =0.60); 1300mJ PEB : 80 $^{\circ}$ C x 120 sec.

